



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	80	V
RMS Reverse Voltage		V _{R(RMS)}	57	V
Forward Continuous Current		I _{FM}	250	mA
Repetitive Peak Forward Current		I _{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0ms @ t = 1.0s	I _{FSM}	3.3 0.5	А

Thermal Characteristics

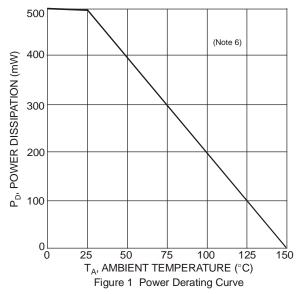
Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 6)	P _D	500	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R _{BJA}	250	/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

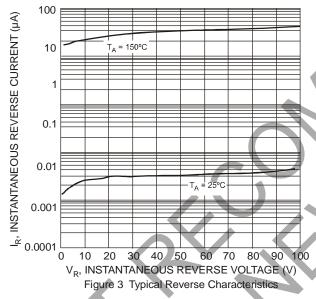
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

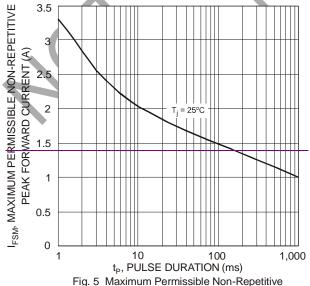
Characteristic	Symbol	Min	Max	Unit	Test Condition	
Reverse Breakdown Voltage (Note 5)	V _{BR(R)}	80		V	$I_R = 1\mu A$	
		_ `	0.715		I _F = 1.0mA	
	_ //		0.72		$I_F = 5.0 \text{mA}$	
Forward Voltage	VF	_	0.855	V	$I_F = 10mA$	
Forward Voltage	VF	_	0.90	V	$I_F = 50 \text{mA}$	
/) / . \		_	1.0		$I_F = 100 \text{mA}$	
			1.25		I _F = 150mA	
			25	nA	V _R = 20V	
			30	30	nA	$V_R = 25V$
Leakage Current (Note 5)	I_R	_	100	nA	$V_R = 80V$	
				30	μΑ	$V_R = 25V, T_J = +150$ °C
			50	μΑ	$V_R = 75V, T_J = +150$ °C	
Total Capacitance	C _T		2.3	pF	$V_R = 0$, $f = 1.0MHz$	
			4.0		$I_F = I_R = 10 \text{mA},$	
Reverse Recovery Time	t _{rr}		4.0	ns	$I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$	

^{5.} Short duration pulse test used to minimize self-heating effect.6. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

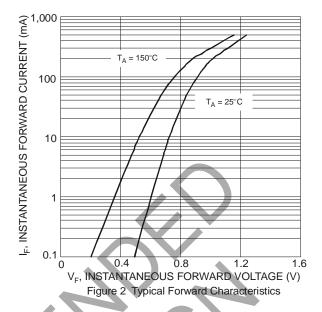


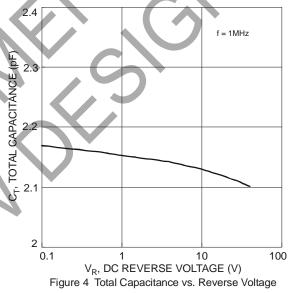


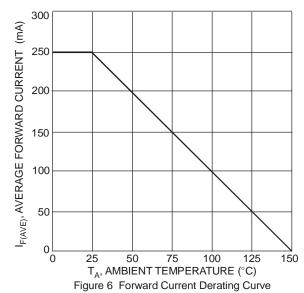




Peak Forward Current as a Function of Pulse Duration



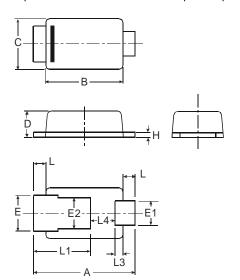






Package Outline Dimensions

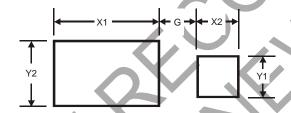
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



POWERDI®323				
Dim	Min	Max	Тур	
Α	2.40	2.60	2.50	
В	1.85	1.95	1.90	
С	1.20	1.30	1.25	
D	0.60	0.70	0.65	
E	0.78	0.98	0.88	
E1	0.50	0.70	0.60	
E2	0.60	1.00	0.80	
H 🏄	0.08	0.18	0.13	
F A	0.20	0.40	0.30	
L1	_	1	1.40	
L3	_	_	0.20	
L4	0.40	0.80	0.60	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.5
X1	2.0
X2	0.8
Y1	0.8
Y2	1.1

NOT RECOMMENDED FOR NEW DESIGN USE 1N4448WSF-7



PD3SD2580

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